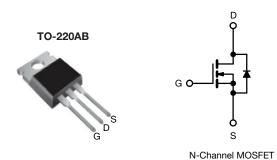
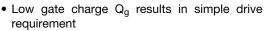
Vishay Siliconix

# **Power MOSFET**



PRODUCT SUMMA	RY	
V <sub>DS</sub> (V)	650	)
$R_{DS(on)}(\Omega)$	$V_{GS} = 10 \text{ V}$	0.93
Q <sub>g</sub> max. (nC)	48	
Q <sub>gs</sub> (nC)	12	
Q <sub>gd</sub> (nC)	19	
Configuration	Sing	le

### **FEATURES**





• Improved gate, avalanche, and dynamic dV/dt ruggedness



- · Fully characterized capacitance and avalanche voltage and current
- · Material categorization: for definitions of compliance please see www.vishav.com/doc?99912

#### Note

This datasheet provides information about parts that are RoHS-compliant and / or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details

## **APPLICATIONS**

- Switch mode power supply (SMPS)
- Uninterruptible power supply
- · High speed power switching

## **TYPICAL SMPS TOPOLOGIES**

- Single transistor flyback
- · Single transistor forward

ORDERING INFORMATION	
Package	TO-220AB
Lead (Pb)-free	IRFB9N65APbF
Lead (Pb)-free and halogen-free	IRFB9N65APbF-BE3

ABSOLUTE MAXIMUM RATINGS ( $T_{\rm C}$	= 25 °C, unle	ess otherwis	e noted)			
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			V <sub>DS</sub>	650		
Gate-source voltage		V <sub>GS</sub>	± 30	V		
Continuous dunin suurant	V -+ 10.V	T <sub>C</sub> = 25 °C		8.5		
Continuous drain current	V <sub>GS</sub> at 10 V	T <sub>C</sub> = 100 °C	I <sub>D</sub>	5.4	Α	
Pulsed drain current a			I <sub>DM</sub>	21	1	
Linear derating factor				1.3	W/°C	
Single pulse avalanche energy b			E <sub>AS</sub>	325	mJ	
Repetitive avalanche current a			I <sub>AR</sub>	5.2	А	
Repetitive avalanche energy <sup>a</sup>			E <sub>AR</sub>	16	mJ	
Maximum power dissipation $T_C = 25  ^{\circ}C$			P <sub>D</sub>	167	W	
Peak diode recovery dV/dt c			dV/dt	2.8	V/ns	
Operating junction and storage temperature range			T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	00	
Soldering recommendations (peak temperature) <sup>d</sup>	For	For 10 s		300	°C	
Mounting torque	6-32 or M3 screw			10	lbf ⋅ in	
Mounting torque	1.1	1.1	N⋅m			

### **Notes**

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11) b. Starting T<sub>J</sub> = 25 °C, L = 24 mH, R<sub>g</sub> = 25  $\Omega$ , I<sub>AS</sub> = 5.2 A (see fig. 12) c. I<sub>SD</sub>  $\leq$  5.2 A, dl/dt  $\leq$  90 A/µs, V<sub>DD</sub>  $\leq$  V<sub>DS</sub>, T<sub>J</sub>  $\leq$  150 °C

- d. 1.6 mm from case



Vishay Siliconix

THERMAL RESISTANCE RAT	INGS			
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient	R <sub>thJA</sub>	-	62	
Case-to-sink, flat, greased surface	R <sub>thCS</sub>	0.50	-	°C/W
Maximum junction-to-case (drain)	R <sub>thJC</sub>	-	0.75	

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-source breakdown voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		650	-	-	V
V <sub>DS</sub> temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference	e to 25 °C, I <sub>D</sub> = 1 mA <sup>d</sup>	-	670	-	mV/°C
Gate-source threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =	= V <sub>GS</sub> , I <sub>D</sub> = 250 μA	2.0	-	4.0	V
Gate-source leakage	I <sub>GSS</sub>		V <sub>GS</sub> = ± 30 V	-	-	± 100	nA
		V <sub>DS</sub> =	$V_{DS} = 650 \text{ V}, V_{GS} = 0 \text{ V}$		-	25	1
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 520 \	/, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C	-	-	250	μA
Drain-source on-state resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 5.1 A <sup>b</sup>	-	-	0.93	Ω
Forward transconductance	9 <sub>fs</sub>	V <sub>DS</sub>	= 50 V, I <sub>D</sub> = 3.1 A	3.9	-	-	S
Dynamic							
Input capacitance	C <sub>iss</sub>	$V_{GS} = 0 V$ ,		-	1417	-	
Output capacitance	C <sub>oss</sub>	1	$V_{DS} = 25 \text{ V},$	-	177	-	1
Reverse transfer capacitance	C <sub>rss</sub>	f = 1	.0 MHz, see fig. 5	-	7.0	-	1
	C <sub>oss</sub>	V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 1.0 V, f = 1.0 MHz	-	1912	-	- pF
Output capacitance			V <sub>DS</sub> = 520 V, f = 1.0 MHz	-	48	-	
Effective output capacitance	C <sub>oss</sub> eff.		V <sub>DS</sub> = 0 V to 520 V <sup>c</sup>	-	84	-	
Total gate charge	Qg		V I <sub>D</sub> = 5.2 A, V <sub>DS</sub> = 400 V see fig. 6 and 13 b	-	-	48	nC
Gate-source charge	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V		-	-	12	
Gate-drain charge	Q <sub>gd</sub>		occ lig. o und 10	-	-	19	
Turn-on delay time	t <sub>d(on)</sub>	$V_{DD}$ = 325 V, $I_{D}$ = 5.2 A $R_{g}$ = 9.1 $\Omega$ , $R_{D}$ = 62 $\Omega$ , see fig. 10 b		-	14	-	ns
Rise time	t <sub>r</sub>			-	20	-	
Turn-off delay time	t <sub>d(off)</sub>			-	34	-	
Fall time	t <sub>f</sub>	1	3	-	18	-	1
Gate input resistance	Rg	f = 1 MHz, open drain		0.5	-	3.3	Ω
<b>Drain-Source Body Diode Characteristic</b>	cs						
Continuous source-drain diode current	I <sub>S</sub>	MOSFET symbol showing the integral reverse p - n junction diode		-	-	5.2	- A
Pulsed diode forward current <sup>a</sup>	I <sub>SM</sub>			-	-	21	
Body diode voltage	V <sub>SD</sub>	$T_J = 25 ^{\circ}\text{C}, I_S = 5.2 \text{A}, V_{GS} = 0 \text{V}^{\text{b}}$		1	-	1.5	V
Body diode reverse recovery time	t <sub>rr</sub>	T 05.00 :	50 A 31/31 400 A / b	-	493	739	ns
Body diode reverse recovery charge	Q <sub>rr</sub>	$T_J = 25  ^{\circ}\text{C}, I_F = 5.2  \text{A}, dI/dt = 100  \text{A/}\mu\text{s}^{\text{b}}$		-	2.1	3.2	μC
Forward turn-on time	t <sub>on</sub>	Intrinsic tu	on is dor	ninated b	v Ls and	L <sub>D</sub> )	

#### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. Pulse width  $\leq$  300 µs; duty cycle  $\leq$  2 %
- c.  $C_{oss}$  eff. is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DS}$
- d. Uses SiHFIB5N65A data and test conditions



## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

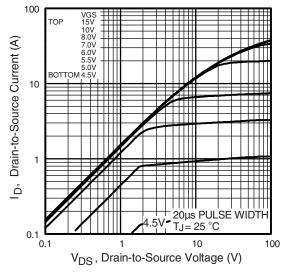


Fig. 1 - Typical Output Characteristics

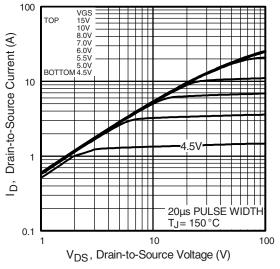


Fig. 2 - Typical Output Characteristics

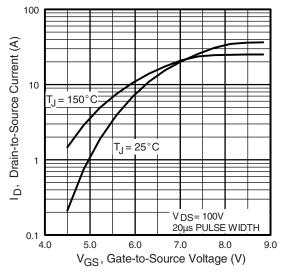


Fig. 3 - Typical Transfer Characteristics

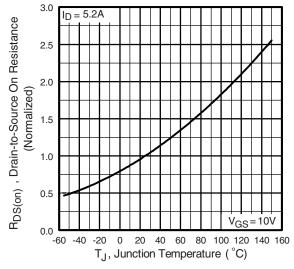


Fig. 4 - Normalized On-Resistance vs. Temperature



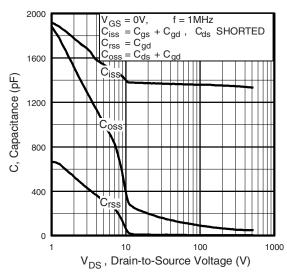


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

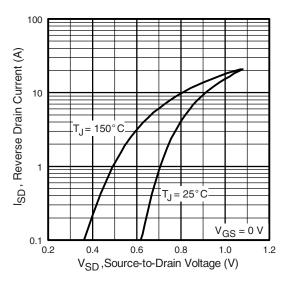


Fig. 7 - Typical Source-Drain Diode Forward Voltage

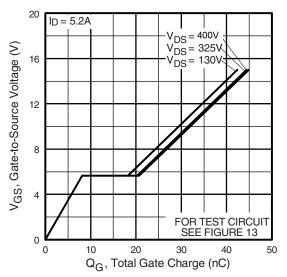


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

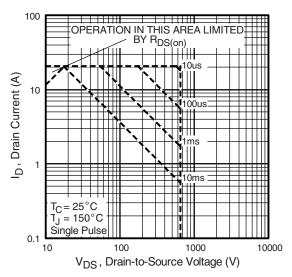


Fig. 8 - Maximum Safe Operating Area



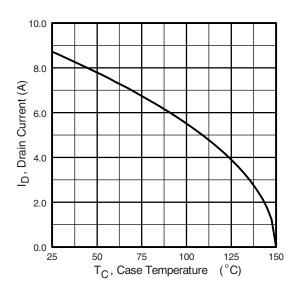


Fig. 9 - Maximum Drain Current vs. Case Temperature

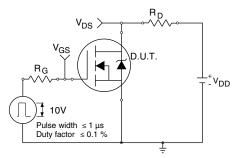


Fig. 10a - Switching Time Test Circuit

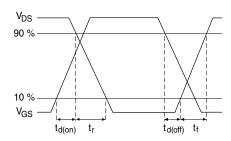


Fig. 10b - Switching Time Waveforms

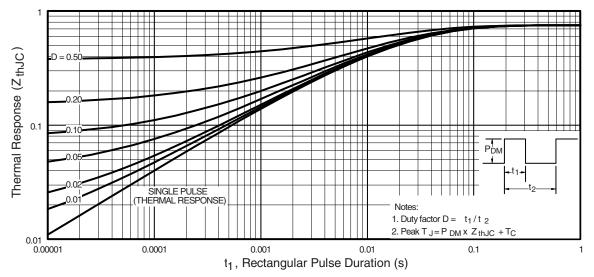


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

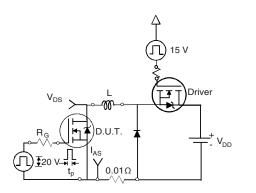


Fig. 12a - Unclamped Inductive Test Circuit

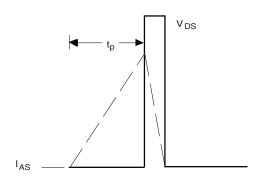


Fig. 12b - Unclamped Inductive Waveforms



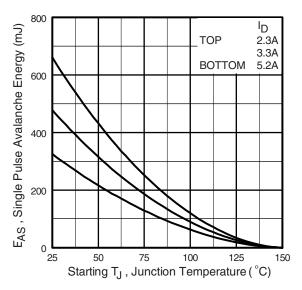


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

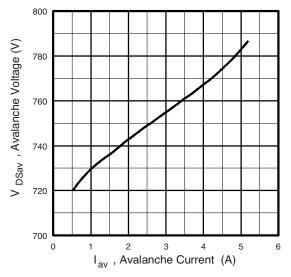


Fig. 12d - Typical Drain-to-Source Voltage vs.
Avalanche Current

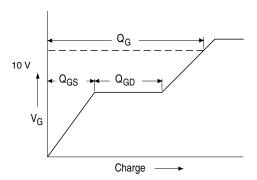


Fig. 13a - Basic Gate Charge Waveform

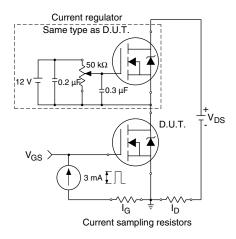
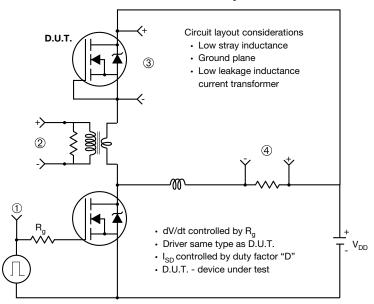


Fig. 13b - Gate Charge Test Circuit



### Peak Diode Recovery dV/dt Test Circuit



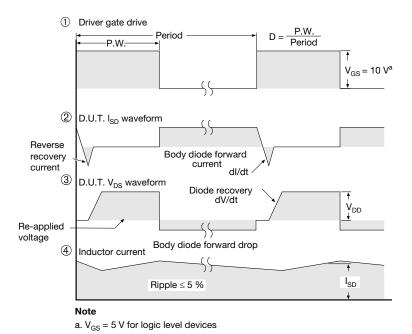


Fig. 14 - For N-Channel

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see <a href="https://www.vishay.com/ppg?91104">www.vishay.com/ppg?91104</a>.



# TO-220-1



DIM.	MILLIM	IETERS	INCHES		
	MIN.	MAX.	MIN.	MAX.	
Α	4.24	4.65	0.167	0.183	
b	0.69	1.02	0.027	0.040	
b(1)	1.14	1.78	0.045	0.070	
С	0.36	0.61	0.014	0.024	
D	14.33	15.85	0.564	0.624	
Е	9.96	10.52	0.392	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.10	6.71	0.240	0.264	
J(1)	2.41	2.92	0.095	0.115	
L	13.36	14.40	0.526	0.567	
L(1)	3.33	4.04	0.131	0.159	
ØΡ	3.53	3.94	0.139	0.155	
Q	2.54	3.00	0.100	0.118	

### Note

DWG: 6031

•  $M^* = 0.052$  inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM



# **Legal Disclaimer Notice**

Vishay

# **Disclaimer**

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and / or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Hyperlinks included in this datasheet may direct users to third-party websites. These links are provided as a convenience and for informational purposes only. Inclusion of these hyperlinks does not constitute an endorsement or an approval by Vishay of any of the products, services or opinions of the corporation, organization or individual associated with the third-party website. Vishay disclaims any and all liability and bears no responsibility for the accuracy, legality or content of the third-party website or for that of subsequent links.

Except as expressly indicated in writing, Vishay products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Vishay product could result in personal injury or death. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.

# **X-ON Electronics**

Largest Supplier of Electrical and Electronic Components

Click to view similar products for MOSFET category:

Click to view products by Vishay manufacturer:

Other Similar products are found below:

614233C 648584F IRFD120 JANTX2N5237 2N7000 FCA20N60\_F109 FDZ595PZ 2SK2545(Q,T) 405094E 423220D

TPCC8103,L1Q(CM MIC4420CM-TR VN1206L 614234A 715780A NTNS3166NZT5G SSM6J414TU,LF(T 751625C

IPS70R2K0CEAKMA1 BUK954R8-60E DMN3404LQ-7 NTE6400 SQJ402EP-T1-GE3 2SK2614(TE16L1,Q) 2N7002KW-FAI

DMN1017UCP3-7 EFC2J004NUZTDG ECH8691-TL-W FCAB21350L1 P85W28HP2F-7071 DMN1053UCP4-7 NTE221 NTE2384

NTE2903 NTE2941 NTE2945 NTE2946 NTE2960 NTE2967 NTE2969 NTE2976 NTE455 NTE6400A NTE2910 NTE2916 NTE2956

NTE2911 US6M2GTR TK10A80W,S4X(S SSM6P69NU,LF